



APPROVAL SHEET

| Approval Specification | Customer's Approval Certificate |
|--|---|
| <p>TO:</p> <p>Part No.:</p> <p>Customer's Part No.:</p> | <p>Please return this copy as a certification of your approval</p> <p>Checked & Approved by:</p> <p>Date:</p> |

BEIJING ZHONGXUN SIFANG SCIENCE & TECHNOLOGY CO.,LTD.

Tel: +86-010-58937383
 Fax: +86-010-58937263
 E-mail: bjzxsf@bjzxsf.net
 Website: <http://www.bjzxsf.net>
 Add: No 201, Block A. Building 3. Yongjie Beilu
 Yongfeng high-tech industrial base
 Haidian District Beijing city



| | | |
|----------|---|------------|
| Part No. | : | SF0442 |
| Pages | : | 6 |
| Date | : | 2014/07/22 |
| Revision | : | 1.1 |

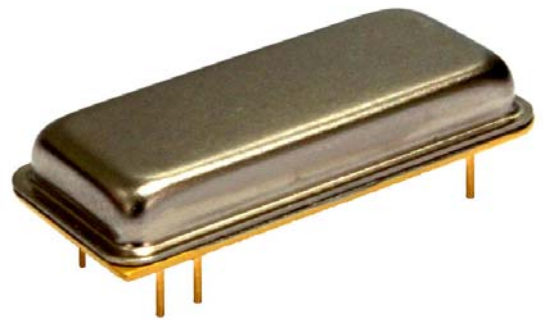
| | |
|---------------------|----|
| Prepared by: | 梁浩 |
| Checked by: | |
| Approved by: | |

Application

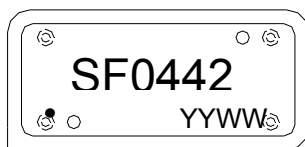
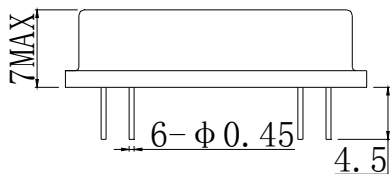
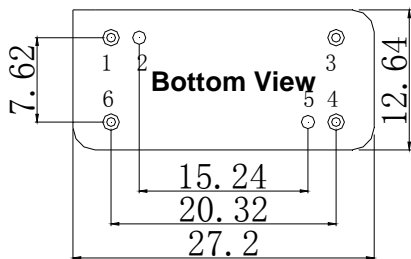
- Low-loss SAW component
- Low amplitude ripple
- Sharp rejections at both out-bands
- Usable passband 2 MHz

Features

- RoHS compatible
- Package size 27.2x12.64x7.00mm³
- Package Code DIP2712J
- Electrostatic Sensitive Device(ESD)



Package Dimensions (Unit: mm)



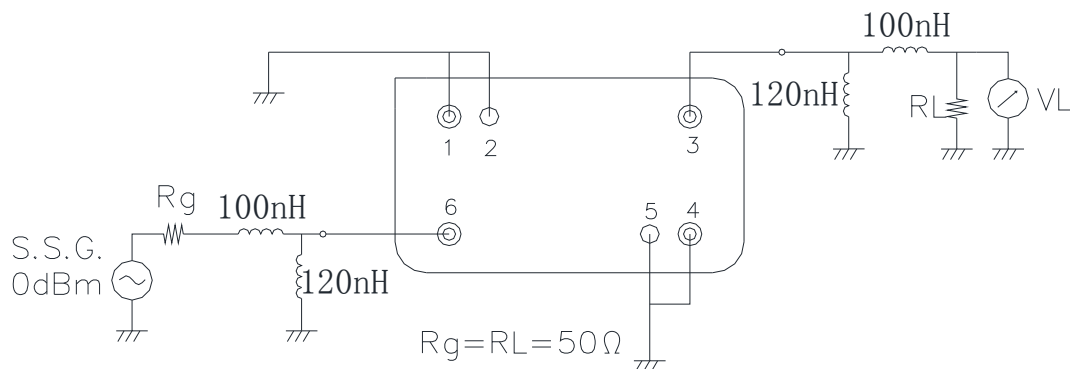
Pin Configuration

| Pin No. | Description |
|---------|-------------|
| 6 | Input |
| 3 | Output |
| 1,2,4,5 | Ground |

Marking Description

| | |
|-------------|-----------------------|
| S | Trademark |
| F | SAW Filter |
| 0442 | Part Number |
| ● | Pin 1 |
| YYWW | Year Code & Week Code |

Test Circuit(Bottom View)



*Fig: If the products produced in 06th week of 2012, The year code & week code is 1206.

Performance**Maximum Rating**

| Item | | Value | Unit |
|-----------------------|-----------|------------|------|
| DC Voltage | V_{DC} | 3 | V |
| Operation Temperature | T | -55 ~ +85 | °C |
| Storage Temperature | T_{stg} | -55 ~ +125 | °C |
| RF Power Dissipation | P | 10 | dBm |

Electronic Characteristics

Test Temperature: $25^{\circ}\text{C} \pm 2^{\circ}\text{C}$

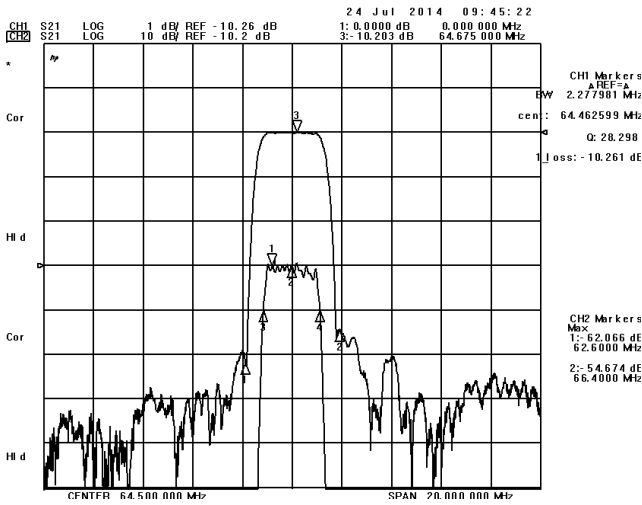
Terminating source impedance: 50Ω

Terminating load impedance: 50Ω

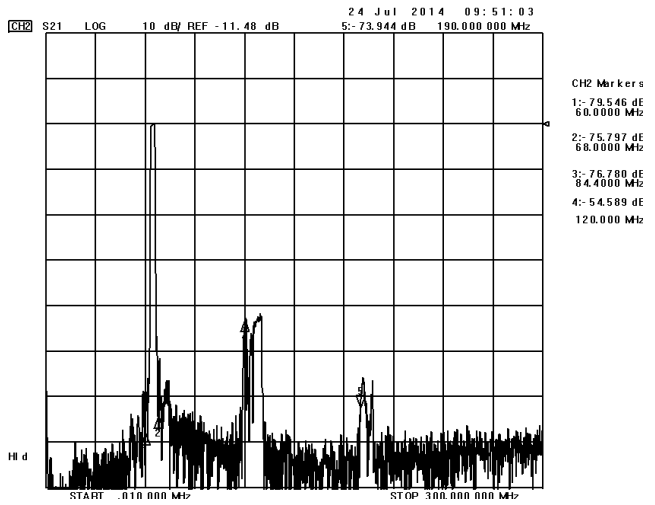
| Item | | Minimum | Typical | Maximum | Unit |
|--------------------------------------|----------------|---------|---------|---------|------|
| Center Frequency | fc | | 64.5 | | MHz |
| Insertion Loss(min) | IL | | 10.3 | 12.5 | dB |
| Amplitude Ripple | $\Delta\alpha$ | | 0.4 | 1.0 | dB |
| 1 dB Bandwidth | BW_{1dB} | 2.00 | 2.28 | 2.30 | MHz |
| 40 dB Bandwidth | BW_{40dB} | | 3.5 | 3.8 | MHz |
| Group Delay Ripple 63.50-65.50MHz | GDR | | 200 | 250 | ns |
| Phase Linearity 63.50-65.50MHz | | | 5 | 10 | deg |
| Absolute Attenuation | α | | | | |
| | 62.60MHz | 40.0 | 53.0 | | dB |
| | 66.40MHz | 40.0 | 45.0 | | dB |
| | 84.40MHz | 50.0 | 65.0 | | dB |

Frequency Characteristics

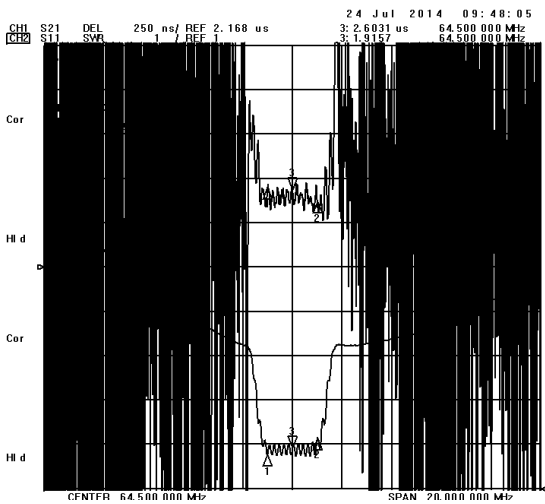
Frequency Response



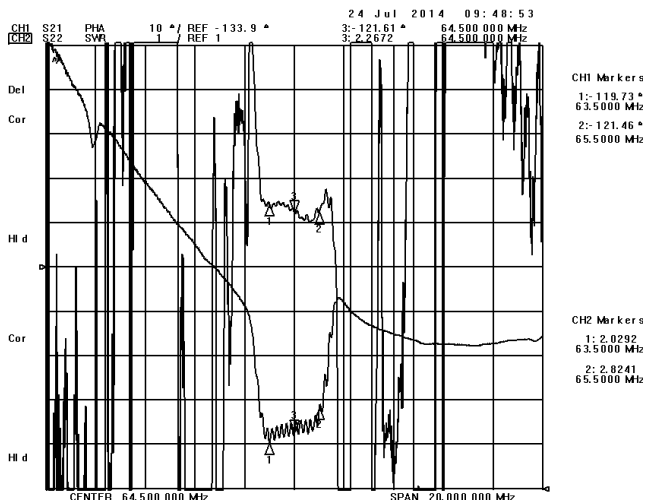
Frequency Response (wideband)



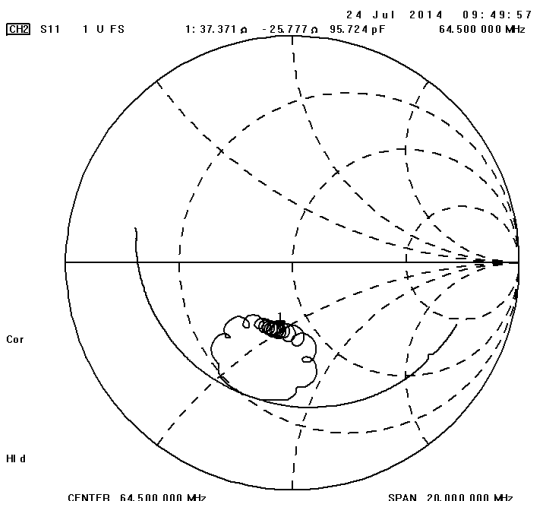
Delay Ripple & S11 VSWR



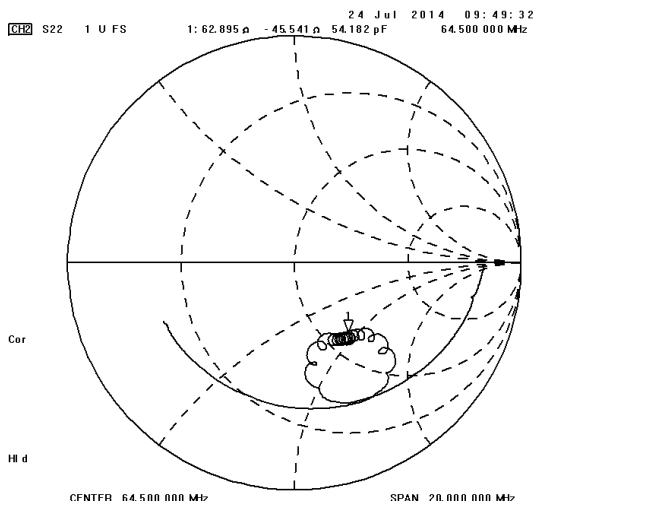
Phase Linearity & S22 VSWR



S11 Smith Chart



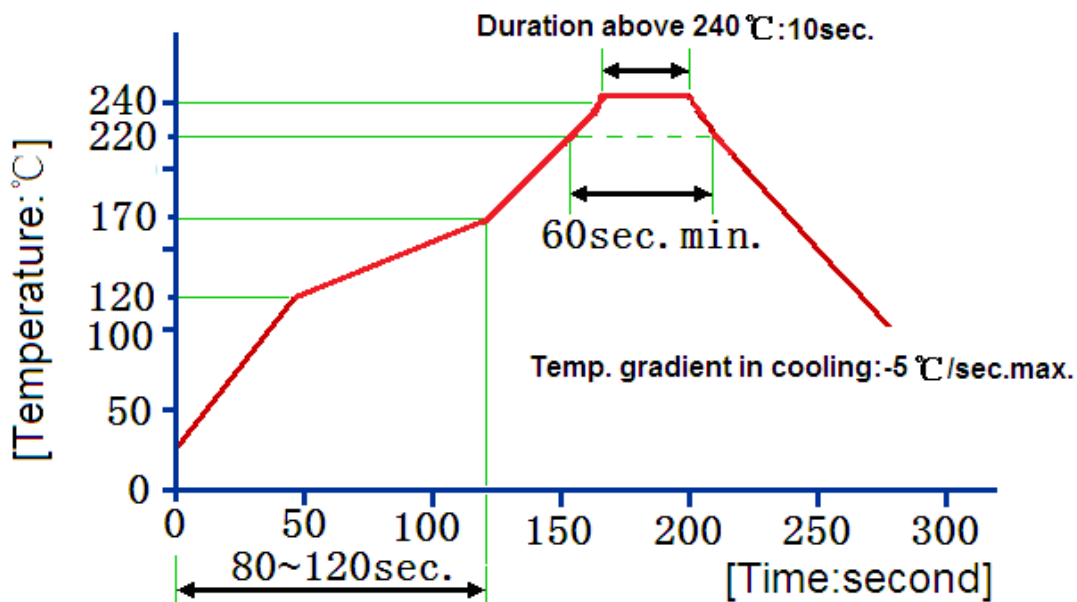
S22 Smith Chart



Reliability (The SAW components shall remain electrical performance after tests)

| No. | Test item | Test condition |
|-----|------------------------------|--|
| 1 | Temperature Storage | (1) Temperature: $85^{\circ}\text{C}\pm 2^{\circ}\text{C}$, Duration: 250h , Recovery time: $2\text{h}\pm 0.5\text{h}$ (2) Temperature: $-55^{\circ}\text{C}\pm 3^{\circ}\text{C}$, Duration: 250h , Recovery time: $2\text{h}\pm 0.5\text{h}$ |
| 2 | Humidity Test | Conditions: $60^{\circ}\text{C}\pm 2^{\circ}\text{C}$, 90~95% RH Duration: 250h |
| 3 | Thermal Shock | Heat cycle conditions: $T_A=-55^{\circ}\text{C}\pm 3^{\circ}\text{C}$, $T_B=85^{\circ}\text{C}\pm 2^{\circ}\text{C}$, $t_1=t_2=30\text{min}$, Switch time: $\leq 3\text{min}$, Cycle time: 100 times, Recovery time: $2\text{h}\pm 0.5\text{h}$. |
| 4 | Vibration Fatigue | Frequency of vibration: 10~55Hz Amplitude: 1.5mm Directions: X,Y and Z Duration: 2h |
| 5 | Drop Test | Cycle time: 10 times Height: 1.0m |
| 6 | Solder Ability Test | Temperature: $245^{\circ}\text{C}\pm 5^{\circ}\text{C}$ Duration: 3.0s--5.0s Depth: DIP--2/3 , SMD--1/5 |
| 7 | Resistance to Soldering Heat | (1) Thickness of PCB: 1mm , Solder condition: $260^{\circ}\text{C}\pm 5^{\circ}\text{C}$, Duration: $10\pm 1\text{s}$ (2) Temperature of Soldering Iron: $350^{\circ}\text{C}\pm 10^{\circ}\text{C}$, Duration: 3~4s , Recovery time : $2 \pm 0.5\text{h}$ |

Recommended Reflow Soldering Diagram



Reflow cycles: 3 cycles max.

Notes

1. As a result of the particularity of inner structure of SAW products, it easy to be breakdown by electrostatic, so we should pay attention to **ESD protect** in the test.
2. **Static voltage** between signal load and ground may cause deterioration and destruction of the component. Please avoid static voltage.
3. **Ultrasonic cleaning** may cause deterioration and destruction of the component. Please avoid ultrasonic cleaning.
4. Only leads of component may **be soldered**. Please avoid soldering another part of component.
5. There is a close relationship between the device's performance and **matching network**. The specifications of this device are based on the test circuit shown above. L and C values may change depending on board layout. Values shown are intended as a guide only.